

U.S. Patent Application 10/014892, filed 11/9/01

Reply to Office Action of 06/21/04

Amendments to the Specification:

Please replace the paragraph bridging pages 7 and 8 with the following amended paragraph:

A coverlay of non-conductive material, such as Kapton film, which has been predrilled with holes corresponding to the locations for the sensor wells (over the electrodes) and coated on the underside with adhesive, such as Pyralux adhesive, is laminated onto the exposed surface of conductive layer 5 [10] and electrode 7 [17] to form non-conductive layer 8 as shown in FIG 5. The well holes in non-conductive layer 8 are configured and placed so that layer 8 completely captures the edges of electrode 7 when it is laminated in place. This prevents any leakage of the sensing current around the electrode. The microsensor package construct is now removed from the mandrel, exposing conductive layer or pad 5 and projection 6 as seen in FIG.6. Referring to FIG.7, Kapton film or other non-conductive sheet material which has been predrilled with holes corresponding to the locations of projections 6 and coated with adhesive may be laminated onto the raised contact side of the package to create the second non-conductive layer, if desired, and thereby complete the microsensor package.